

# EVVOSEMI<sup>®</sup>

THINK CHANGE DO



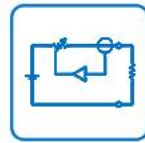
ESD



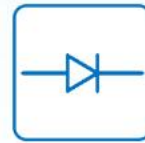
TVS



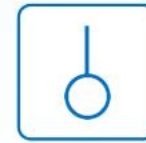
MOS



LDO



Diode



Sensor



DC-DC

## Product Specification

▶ Domestic	Part Number	IRF9956
▶ Overseas	Part Number	IRF9956
▶ Equivalent	Part Number	IRF9956

EV is the abbreviation of name EVVO

**30V N+N-Channel Enhancement Mode MOSFET**

**General Description**

The IRF9956 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent R<sub>DS(ON)</sub> and gate charge for most of the small power switching and load switch applications. They meet the RoHS and Product requirement with full function reliability approved.

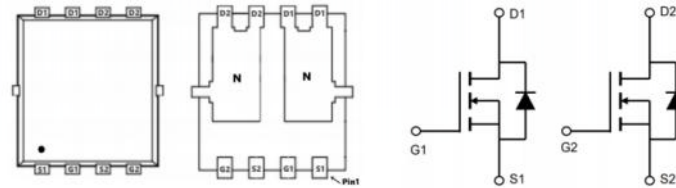
**Application**

- Battery protection
- Load switch
- Uninterruptible power supply

**General Features**

- V<sub>DS</sub> = 30V I<sub>D</sub> = 12A
- R<sub>DS(ON)</sub> < 8.5mΩ @ V<sub>GS</sub>=10V
- R<sub>DS(ON)</sub> < 13 mΩ @ V<sub>GS</sub>=4.5V

**SOP-8 Pin Configuration**



**Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	12	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	10	A
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	9.5	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	7.6	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	40	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	20	mJ
I <sub>AS</sub>	Avalanche Current	22	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	1.7	W
P <sub>D</sub> @T <sub>A</sub> =70°C	Total Power Dissipation <sup>4</sup>	1.08	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	75	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	4.8	°C/W

**30V N+N-Channel Enhancement Mode MOSFET**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1mA$	---	0.023	---	V/ $^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=15A$ $V_{GS}=4.5V, I_D=10A$	6.8 8	---	8.5 13	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	---	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.08	---	mV/ $^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=24V, V_{GS}=0V, T_J=25^\circ\text{C}$ $V_{DS}=24V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	1 5	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=15A$	---	24.4	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.8	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=15V, V_{GS}=4.5V, I_D=12A$	---	9.82	---	nC
$Q_{gs}$	Gate-Source Charge		---	2.24	---	
$Q_{gd}$	Gate-Drain Charge		---	5.54	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15V, V_{GS}=10V, R_G=1.5\Omega$ $I_D=20A$	---	6.4	---	ns
$T_r$	Rise Time		---	39	---	
$T_{d(off)}$	Turn-Off Delay Time		---	21	---	
$T_f$	Fall Time		---	4.7	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	896	---	pF
$C_{oss}$	Output Capacitance		---	126	---	
$C_{rss}$	Reverse Transfer Capacitance		---	108	---	
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	---	---	37	A
$I_{SM}$	Pulsed Source Current <sup>2,5</sup>		---	---	75	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3 .The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=22A$
- 4.The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
- 5 .The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.



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Typical Characteristics

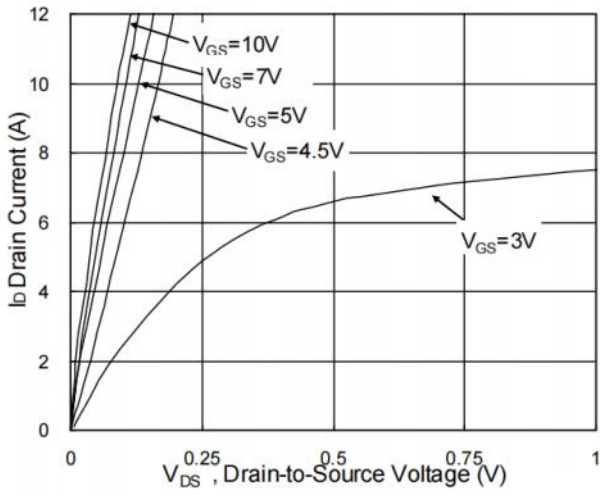


Fig.1 Typical Output Characteristics

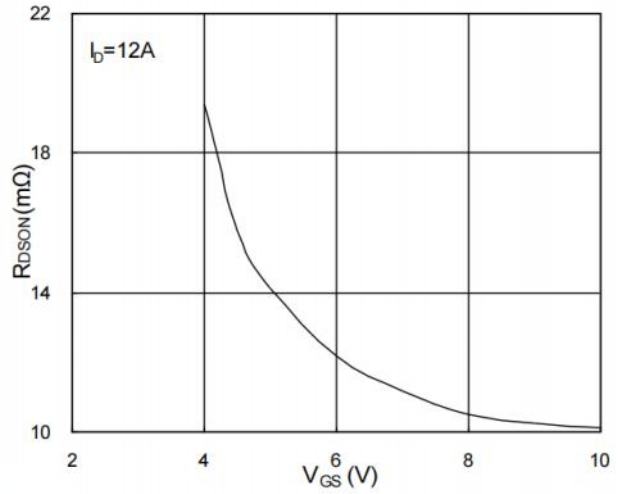


Fig.2 On-Resistance vs. G-S Voltage

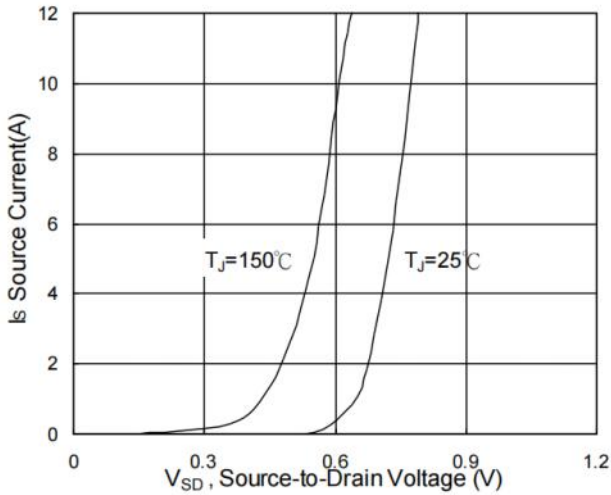


Fig.3 Forward Characteristics of Reverse

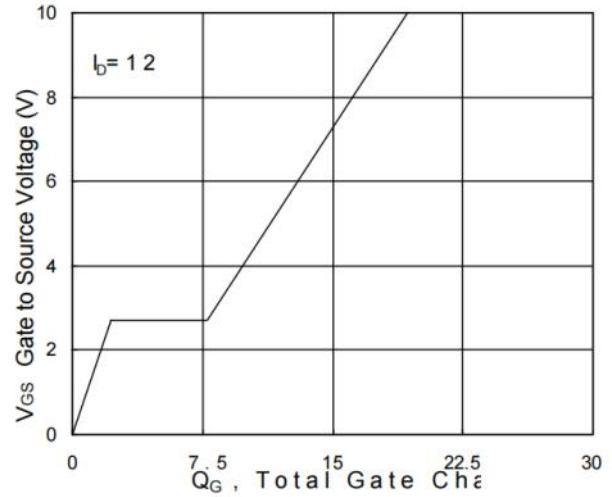


Fig.4 Gate-charge Characteristics

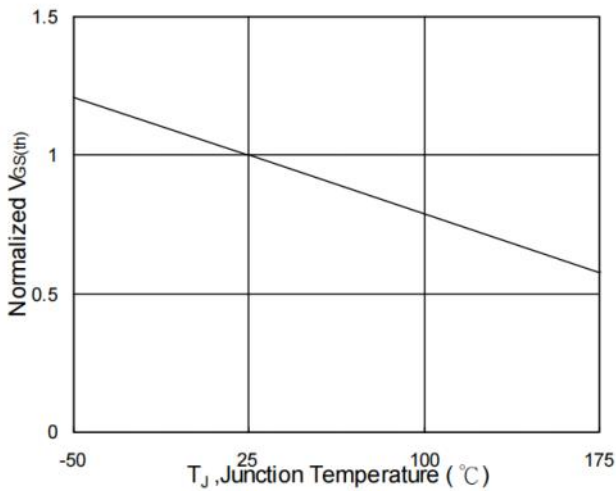


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

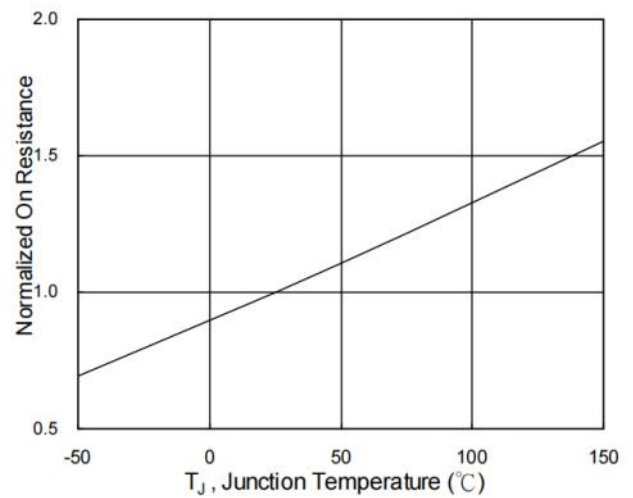


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

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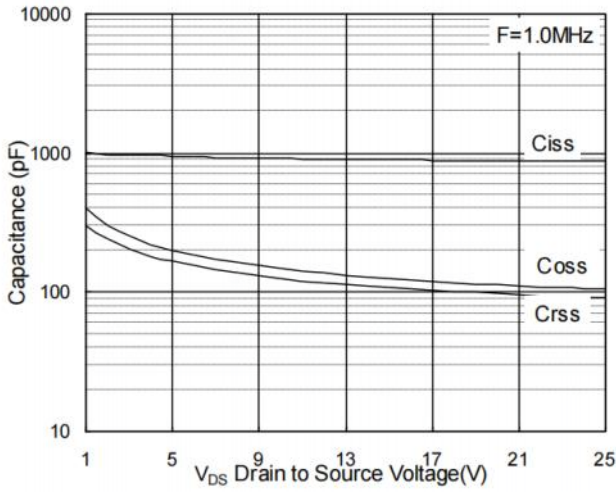


Fig.7 Capacitance

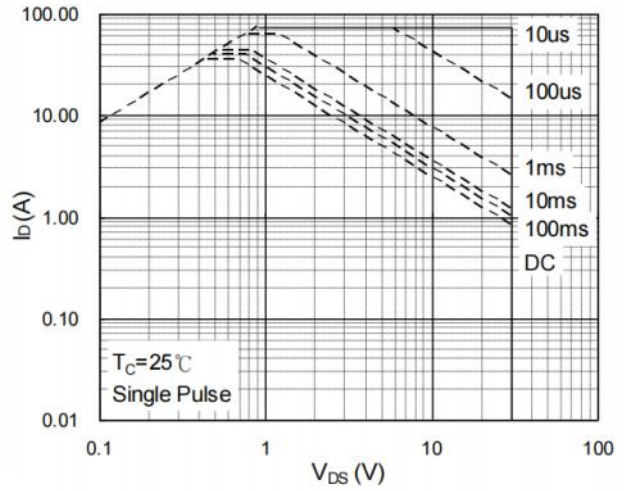


Fig.8 Safe Operating Area

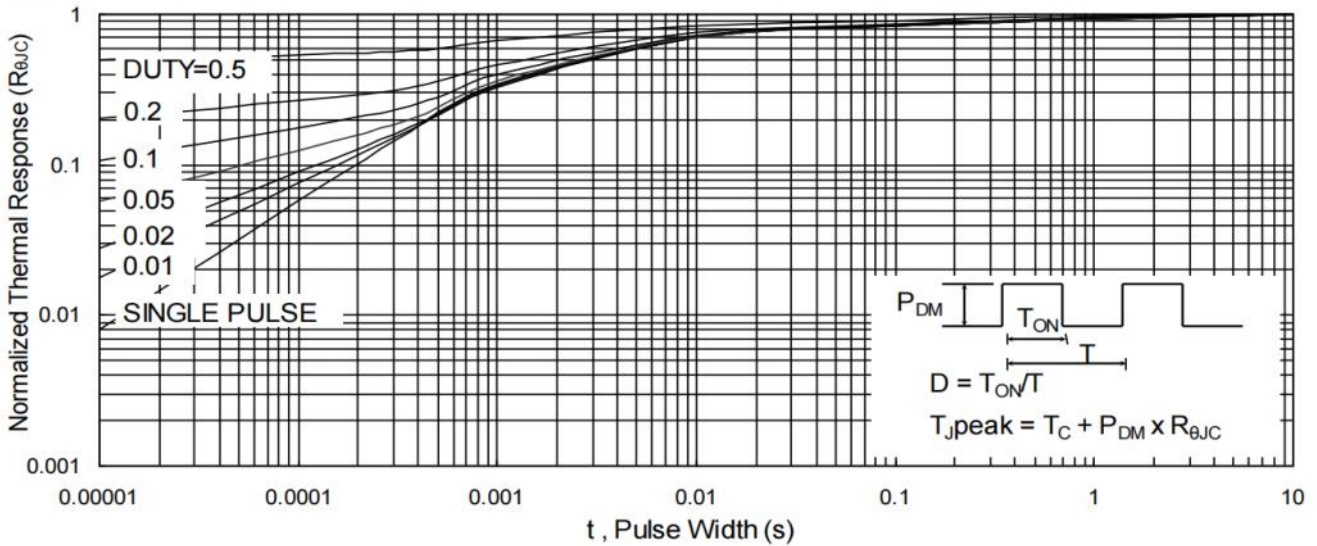


Fig.9 Normalized Maximum Transient Thermal Impedance

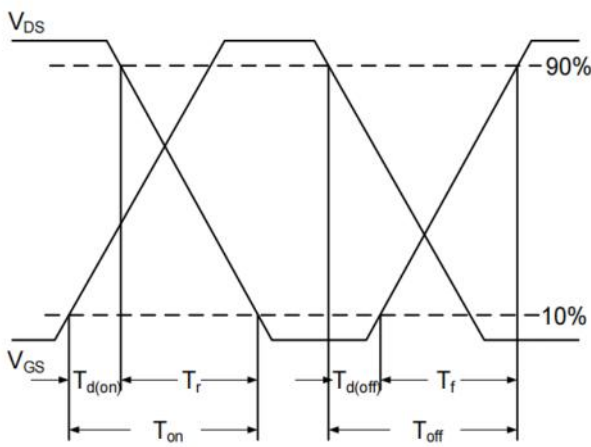


Fig.10 Switching Time Waveform

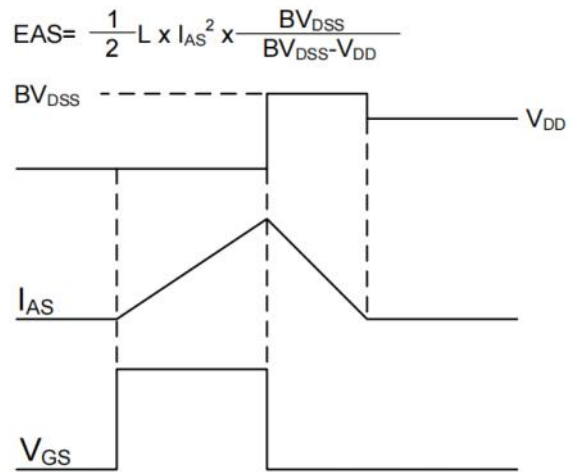
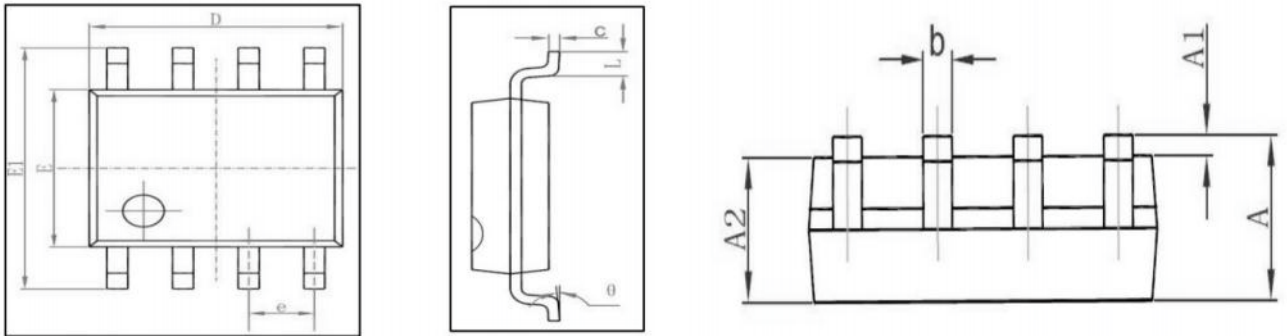


Fig.11 Unclamped Inductive Waveform

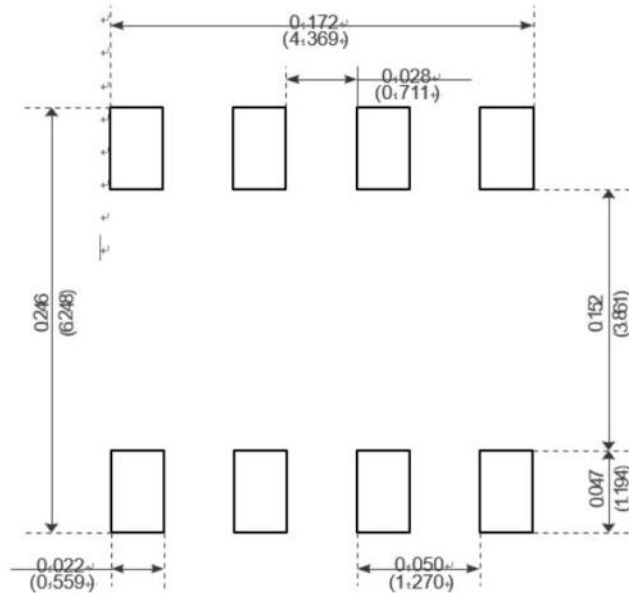
$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

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**Package Mechanical Data-SOP-8**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads



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